



Material Content Data Sheet



Sales Product Name		ICE3A2065		Issued		29. August 2013		
MA#		MA001054980						
Package		PG-DIP-8-6		Weight*		538.33 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.194	0.96	0.96	9649	9649
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.01		99	
	non noble metal	zinc	7440-66-6	0.213	0.04		396	
	non noble metal	iron	7439-89-6	4.266	0.79		7925	
wire	non noble metal	copper	7440-50-8	173.237	32.18	33.02	321807	330227
	noble metal	gold	7440-57-5	0.384	0.07	0.07	714	714
	encapsulation	organic material	carbon black	1333-86-4	1.727	0.32		3209
encapsulation	inorganic material	antimonytrioxide	1309-64-4	6.910	1.28		12836	
	plastics	brominated resin	-	6.910	1.28		12836	
	plastics	epoxy resin	-	39.732	7.38		73806	
	inorganic material	silicondioxide	60676-86-0	290.215	53.93	64.19	539105	641792
leadfinish	non noble metal	tin	7440-31-5	7.496	1.39	1.39	13925	13925
plating	noble metal	silver	7440-22-4	0.832	0.15	0.15	1546	1546
glue	plastics	epoxy resin	-	0.202	0.04		376	
	noble metal	silver	7440-22-4	0.954	0.18	0.22	1771	2147
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

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